PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT2975444

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
VENKATRAMAN IYER	06/20/2013
DARREN S. JUE	07/08/2013
RAHUL R. SHAH	08/02/2013
ARVIND A. KUMAR	09/02/2013

RECEIVING PARTY DATA

Name:	INTEL CORPORATION
Street Address:	2200 MISSION COLLEGE BLVD.
City:	SANTA CLARA
State/Country:	CALIFORNIA
Postal Code:	95054

PROPERTY NUMBERS Total: 1

Property Type	Number
PCT Number:	US2013032708

CORRESPONDENCE DATA

Fax Number: (612)332-8352

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 503-712-4988
Email: inteldocs@cpaglobal.com
Correspondent Name: INTEL CORPORATION
Address Line 1: C/O CPA GLOBAL
Address Line 2: PO BOX 52050
Address Line 4: MINNEAPOLIS, MINNESOTA 55402

ATTORNEY DOCKET NUMBER:	P50882PCT
NAME OF SUBMITTER:	PRIYA AGGARWAL
SIGNATURE:	//priya aggarwal//
DATE SIGNED:	08/11/2014

Total Attachments: 8
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ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

VENKATRAMAN IYER; DARREN S. JUE; RAHUL R. SHAH; ARVIND KUMAR

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95054 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all inventions and improvements that are disclosed in the International application entitled:

HIGH PERFORMANCE INTERCONNECT PHYSICAL LAYER

(I hereby authorize and request my attorney, associated with Customer Number 97298, to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on **March 15, 2013** as

International Application Number **PCT/US2013/032708** and

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said International application and all related applications (e.g. national phase applications, divisional applications, continuation applications, reexaminations, reissues, and the like) that have been or shall be filed in the United States and/or all foreign countries on said inventions and improvements, as well as in and to all rights of priority resulting from the filing of said International application;

agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Venkatraman Iyer 6/20/2013
IYER, Venkatraman (Today's Date)

JUE, Darren S. (Today's Date)

SHAH, Rahul C. (Today's Date)

KUMAR, Arvind A. (Today's Date)

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agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all design, utility, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

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IYER, Venkatraman (Today's Date)

7/8/13

JUE, Darren S. (Today's Date)

SHAH, Rahul C. (Today's Date)

KUMAR, Arvind A. (Today's Date)

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RRS

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International Application Number PCT/US2013/032708 and

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IYER, Venkatraman	(Today's Date)
JUE, Darren S.	(Today's Date)
SHAH, Rahul ~~C~~. R RCS	08/02/2013 (Today's Date)
KUMAR, Arvind A.	(Today's Date)

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International Application Number __PCT/US2013/032708__ and

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IYER, Venkatraman (Today's Date)

JUE, Darren S. (Today's Date)

SHAH, Rahul C. (Today's Date)

Sept 2nd 2013

KUMAR, Arvind A. (Today's Date)